



	XCB170	Units
Load Voltage	350	V
Load Current	100	mA
Max R_{ON}	50	Ω

Features

- Small 6 Pin DIP Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- 3750V_{RMS} Input/Output Isolation
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hookswitch
 - Dial Pulsing
 - Ground Start
 - Ringer Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
 - Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The XCB170 is a 1-Form-B relay which uses optically coupled MOSFET technology to provide 3750V of input to output isolation. The efficient MOSFET switches and photovoltaic die use Clare's patented OptoMOS® architecture. A highly efficient GaAlAs infrared LED controls the optically coupled input. The device is available in small 6-pin dual in line package in standard through hole and surface mount lead bend.

Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- BSI Certified to:
 - BS EN 60950:1992 (BS7002:1992)
Certificate #: 7344
 - BS EN 41003:1993
Certificate #: 7344

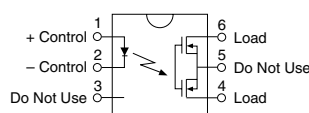
Ordering Information

Part #	Description
XCB170	6 Pin DIP (50/Tube)
XCB170S	6 Pin Surface Mount (50/Tube)
XCB170STR	6 Pin Surface Mount (1000/Reel)

Pin Configuration

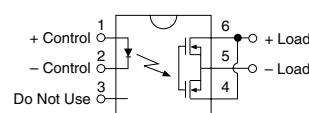
XCB170 Pinout

AC/DC Configuration

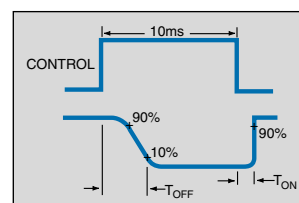


XCB170 Pinout

DC Only Configuration



Switching Characteristics of Normally Closed (Form B) Devices



**Absolute Maximum Ratings (@ 25° C)**

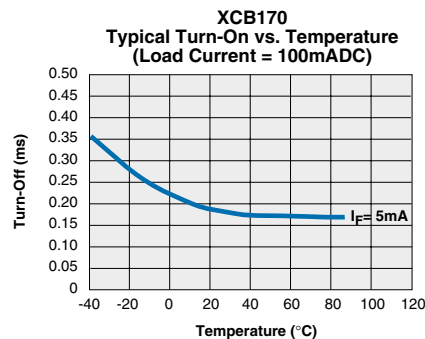
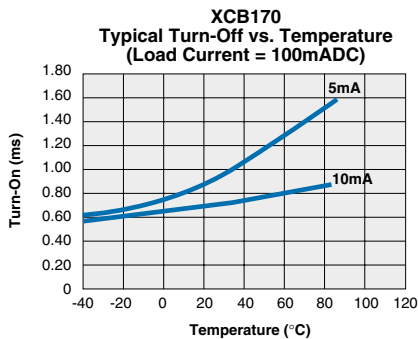
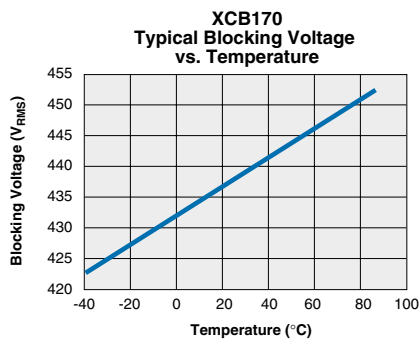
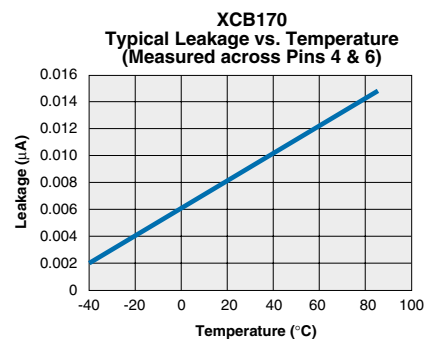
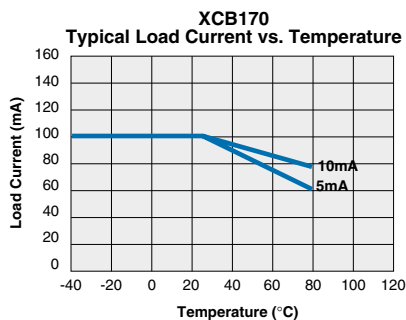
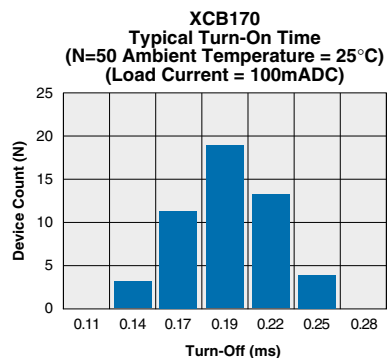
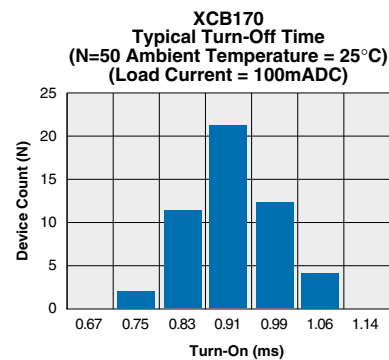
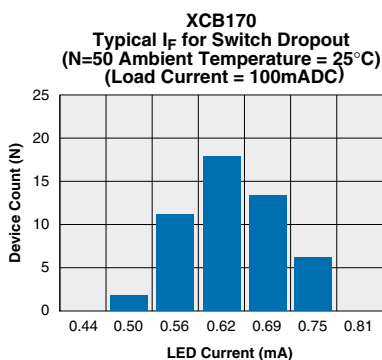
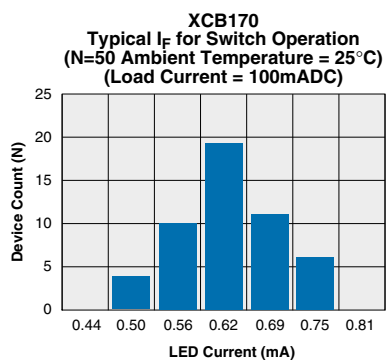
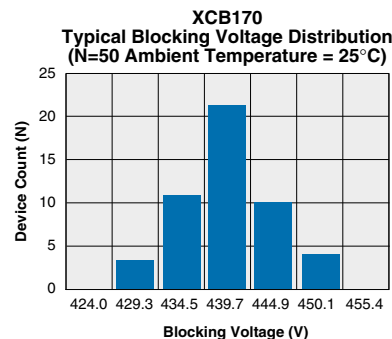
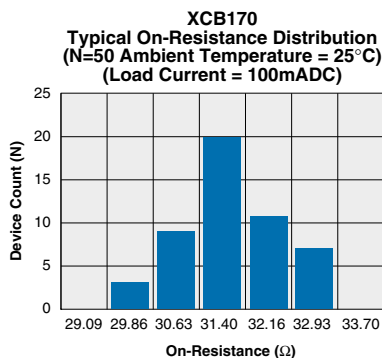
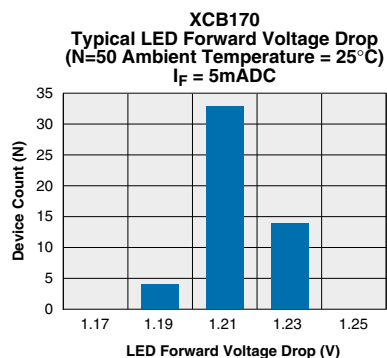
Parameter	Min	Typ	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	50	mA
Peak (10ms)	-	-	1	A
Reverse Input Voltage	-	-	5	V
Total Power Dissipation	-	-	800 ²	mW
Isolation Voltage Input to Output	3750	-	-	V _{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature DIP Package	-	-	+260	°C
Surface Mount Package (10 Seconds Max.)	-	-	+220	°C

¹ Derate Linearly 1.33 mW/°C² Derate Linearly 6.67 mW/°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Electrical Characteristics

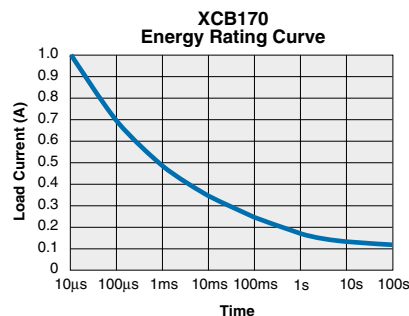
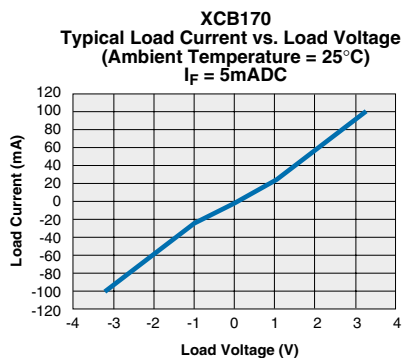
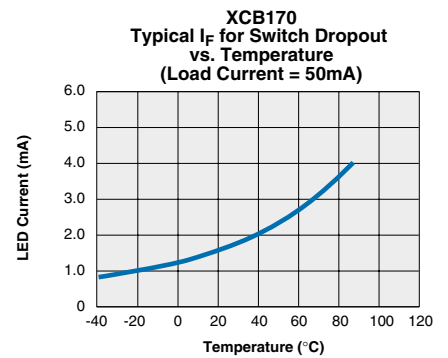
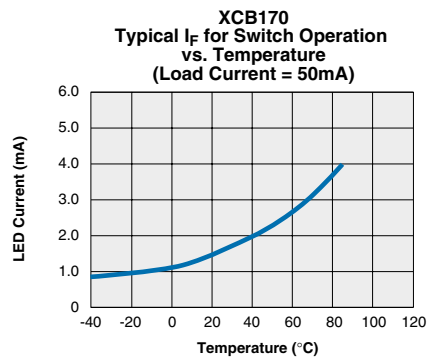
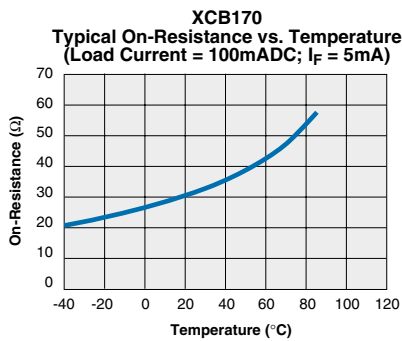
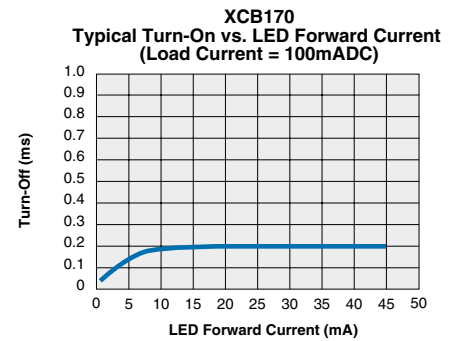
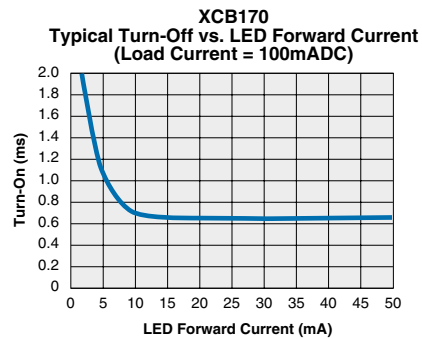
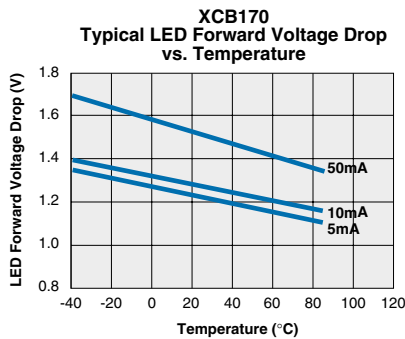
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Load Voltage (Peak)	-	V _L	-	-	350	V
Load Current (Continuous) AC/DC Configuration	-	I _L	-	-	100	mA
DC Configuration	-	I _L	-	-	180	mA
Peak Load Current	10ms	I _{LPK}	-	-	350	mA
On-Resistance AC/DC Configuration	I _L =120mA	R _{ON}	-	31	50	Ω
DC Configuration	I _L =200mA	R _{ON}	-	10	15	Ω
Off-State Leakage Current	V _L =350V	I _{LEAK}	-	-	1	μA
Switching Speeds Turn-On	I _F =5mA, V _L =10V	T _{ON}	-	-	5	ms
Turn-Off	I _F =5mA, V _L =10V	T _{OFF}	-	-	5	ms
Output Capacitance	50V; f=1MHz	C _{OUT}	-	25	-	pF
Capacitance Input to Output	-	-	-	3	-	pF
Input Characteristics @ 25°C						
Input Control Current	I _L =120mA	I _F	5	-	50	mA
Input Dropout Current	-	I _F	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF

PERFORMANCE DATA*


* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



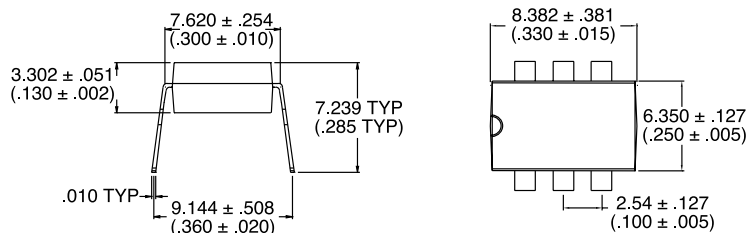
PERFORMANCE DATA*



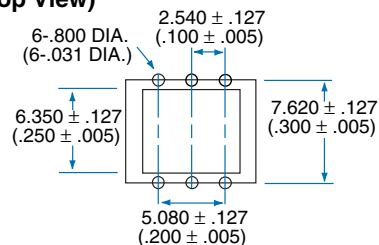
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MECHANICAL DIMENSIONS

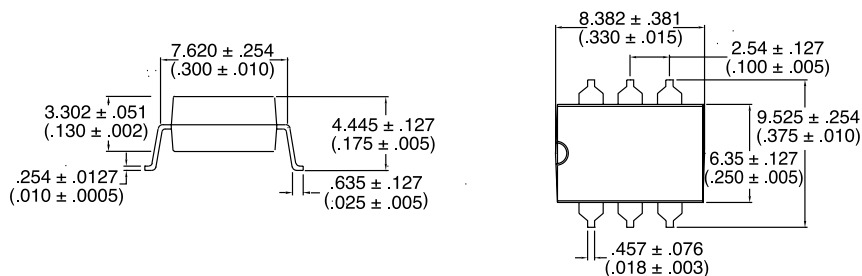
6Pin DIP Through Hole (Standard)



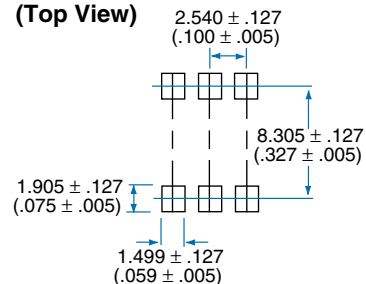
PC Board Pattern (Top View)



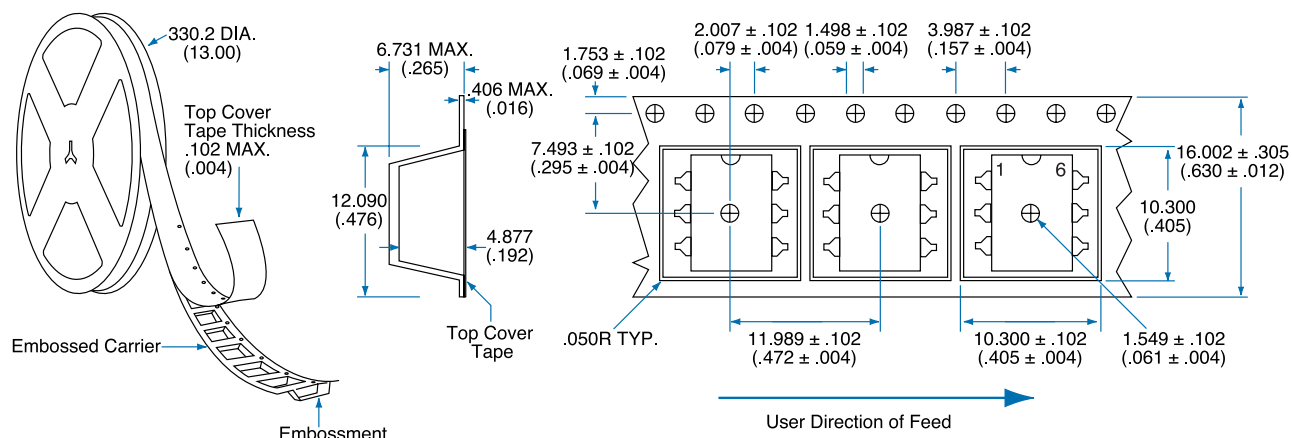
6Pin DIP Surface Mount ("S" Suffix)



PC Board Pattern (Top View)



Tape and Reel Packaging for 6 Pin Power DIP Surface Mount Package



Dimensions
mm
(inches)



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